

S			VA	RIA	TIONS)		
SYMBO		AA		Į O Z		AB		40 Z
0	MIN.	NOM.	MAX.	ĪĒ	MIN.	NOM.	MAX.	Ť
D	.940	.960	.980		.990	1.010	1.030	
D1		.800 BSC				.850 BSC		
Ε	.940	.960	.980		.990	1.010	1.030	
E1	ł	.800 BSC				.850 BSC		
М	_	17	_	3	_	18		3
N	_	_	288	4	, -	_	323	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5	, 11, 16						
REF	10-324							
ISSUE	Α							

		AC		ο̈́		AD		102
	MIN	NOM	MAX		MIN	NOM	MAX	T E
D	1.040	1.060	1.080		1.090	1.110	1.130	
D1		.900 BSC				.950 BSC		
E	1.040	1.060	1.080		1.090	1.110	1.130	
E1		.900 BSC				.950 BSC		1
М	_	19	_	3	_	20	_	3
N	_	-	360	4	_	_	399	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5	, 11, 16						
REF	10-324	4						
ISSUE	Α			·				

		ΑE		Į O Į		AF		TO Z
	MIN	NOM	MAX	ĪĒ	MIN	NOM	MAX	TE
D	1.140	1.160	1.180		1.190	1.210	1.230	
D1		1.000 BSC				1.050 BSC		
Ε	1.140	1.160	1.180		1.190	1.210	1.230	
E1		1.000 BSC				1.050 BSC		
М	_	21	-	3		22	_	3
N	_	_	440	4	_	_	483	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5,	11, 16						
REF	10-324	•	_					
ISSUE	Α							, i

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S		VARIATIONS										
SYMBO.		AG		102		AH		0.2				
O L	MIN.	NOM.	MAX.	ĪĒ	MIN.	NOM.	MAX.	Ť				
D	1.240	1.260	1.280		1.290	1.310	1.330					
D1		1.100 BSC				1.150 BSC						
E	1.240	1.260	1.280		1.290	1.310	1.330					
E1		1.100 BSC				1.150 BSC						
M	_	23		3		24	-	3				
N	-	_	528	4		-	575	4				
S		.000 BSC		14		.025 BSC		14				
NOTE_	1, 2, 5,	, 11, 16										
REF	10-324	1										
ISSUE	Α											

		AJ		N O		AK		02
	MIN	NOM	MAX	ĪĒ	MIN	NOM	MAX	TE
D	1.340	1.360	1.380		1.390	1.410	1.430	
D1		1.200 BSC				1.250 BSC		
E	1.340	1.360	1.380		1.390	1.410	1.430	
E1		1.200 BSC				1.250 BSC		
М	-	25	_	3	_	26	_	3
N	_	_	624	4			675	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5	, 11, 16						
REF	10-324	4						
ISSUE	Α							

		AL		Ŋ		AM		Q Z
	MIN	NOM	MAX	E	MIN	NOM	MAX	E
D	1.440	1.460	1.480		1.490	1.510	1.530	
D1		1.300 BSC				1.350 BSC		
·Ε	1.440	1.460	1.480		1.490	1.510	1.530	
E1		1.300 BSC	,			1.350 BSC		
М		27		3		28	_	3
N	_	_	728	4	-		783	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5	, 11, 16						
REF	10-324	1						
ISSUE	Α							

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-м во		AN		J O Z		AP		Q Q
0	MIN.	NOM.	MAX.	Ē	MIN.	NOM.	MAX.	T E
D	1.540	1.560	1.580		1.590	1.610	1.630	
D1		1.400 BSC	* • • • • • • • • • • • • • • • • • • •			1.450 BSC		
Ε	1.540	1.560	1.580		1.590	1.610	1.630	
E1		1.400 BSC				1.450 BSC		
М		29	_	3	-	30	_	3
N	-	_	840	4	<u> </u>	-	899	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5	, 11, 16						
REF	10-32	4	**					
ISSUE	Α	- · · -						

		AR		Ŋ	•	AT		N O
	MIN	NOM	MAX	TE	MIN	NOM	MAX] [E
D	1.640	1.660	1.680		1.690	1.710	1.730	
D1		1.500 BSC				1.550 BSC		
E	1.640	1.660	1.680		1.690	1.710	1.730	
E1		1.500 BSC				1.550 BSC		
М	_	31	_	3	_	32	-	3
N	_	_	960	4	-	_	1023	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5	, 11, 16						
REF	10-324	4						
ISSUE	Α							

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		AU		Į O Z		AV		102
	MIN	NOM	MAX	E	MIN	NOM	MAX	E
D	1.740	1.760	1.780		1.790	1.810	1.830	
D1		1.600 BSC				1.650 BSC		
Ε	1.740	1.760	1.780		1.790	1.810	1.830	
E1	-	1.600 BSC				1.650 BSC		
М	_	33	_	3	_	34	_	3
N		_	1088	4		_	1155	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5,	, 11, 16						
REF	10-324							
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-M B O		AW		ţ O Z		AY		102		
C	MIN.	NOM.	MAX.	ĪĒ	MIN.	NOM.	MAX.	Ť		
D	1.840	1.860	1.880		1.890	1.910	1.930			
D1		1.700 BSC				1.750 BSC				
Ε	1.840	1.860	1.880		1.890	1.910	1,930			
E1		1.700 BSC				1.750 BSC				
М	_	35	_	3	_	36		3		
N	_	_	1224	4	_	_	1295	4		
S		.000 BSC		14		.025 BSC		14		
NOTE	1, 2, 5,	11, 16								
REF	10-324									
ISSUE	Α									

	AAA				AAB			
	MIN	NOM	MAX	Q	MIN	NOM	MAX	O T E
D	1.940	1.960	1.980		1.990	2.010	2.030	
D1		1.800 BSC				1.850 BSC		
Ε	1.940	1.960	1.980		1.990	2.010	2.030	1
E1		1.800 BSC				1.850 BSC		1
М	-	37	_	3	-	38	_	3
N	_	-	1368	4	_	-	1443	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5,	, 11, 16						
REF	10-324	ļ						
ISSUE	Α							

		AAC		NO	AAD			
	MIN	NOM	MAX] [MIN	NOM	MAX	O T E
D	2.040	2.060	2.080		2.090	2.110	2.130	
D1		1.900 BSC				1.950 BSC		
E	2.040	2.060	2.080		2.090	2.110	2.130	
E1		1.900 BSC				1.950 BSC		
М	_	39	-	3	_	40	_	3
N	_	_	1520	4	-	-	1599	4
S		.000 BSC		14		.025 BSC		14
NOTE	1, 2, 5	, 11, 16						
REF	10-324	ļ						
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S	VARIATIONS									
М В О		AAE		Į Q Z				Ž Q Z		
0	MIN.	NOM.	MAX.	Ē	MIN.	NOM.	MAX.	T E		
D	2.140	2.160	2.180							
D1		2.000 BSC								
Ε	2.140	2.160	2.180							
E1		2.000 BSC								
М	_	41	_	3						
N	_	_	1680	4	,					
S		.000 BSC		14						
NOTE	1, 2, 5	, 11, 16								
REF	10-32	4								
ISSUE	A									

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NOTES:

- 1 DIMENSIONING PER ANSI Y14.5M-1982.
- 2 PIN POSITION DESIGNATION PER JEDEC STANDARD 95-1, SPP-010
- 3 "M" REPRESENTS THE PIN MATRIX SIZE.
- 4 "N" REPRESENTS THE MAXIMUM ALLOWABLE NUMBER OF PINS.
- 5 22 x 22 MATRIX SIZE IS SHOWN FOR ILLUSTRATION ONLY.

6	THIS I	DIMEN	ISION	SPECII	FIES	THE	MAXIMUM	LID	HEIGHT	FOR	вотн
							RATIONS.				

DIMENSION "A" DOES NOT INCLUDE INTEGRAL HEATSINK OR ATTACHED FEATURES.

8 THE SEATING PLANE IS DEFINED BY THE PIN TIPS FOR BOTH CAVITY UP AND DOWN CONFIGURATIONS.

9 -C- IS THE PLANE OF THE PIN TO PACKAGE INTERFACE FOR BOTH CAVITY UP AND DOWN CONFIGURATION SHOWN FOR ILLUSTRATION ONLY).

PIN DIAMETER INCLUDES PLATING BUT DOES NOT INCLUDE SOLDER DIP FINISH.

A1 CORNER IDENTIFIED BY CHAMFER. ADDITIONAL ID TYPES ARE OPTIONAL AND MAY CONSIST OF METALLIZED MARKINGS OR OTHER FEATURES.

THERE MUST BE .010" MINIMUM SPACING BETWEEN ANY TWO METALLIZED FEATURES ON THE PACKAGE.

PINS AND BRAZE FILLETS MUST BE POSITIONED ENTIRELY ON THE BRAZE PADS.

S IS MEASURED WITH RESPECT TO -A- AND -B- AND DEFINES

THE POSITION OF THE CENTER PIN IN THE OUTER ROW, WHEN THERE IS AN ODD NUMBER OF PINS IN THE OUTER ROW, S = .000", WHEN AN EVEN NUMBER IS USED, S = .025". ALL PINS IN A GIVEN ROW MUST BE ON A .050" GRID.

SEE APPLICATION NOTES.

16 ALL DIMENSIONS ARE IN INCHES.

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APPLICATION NOTES:

- A FOR SOME SOCKETING APPLICATIONS IN CAVITY UP ORIENTATION AN AREA ON THE TOP SURFACE OF THE PACKAGE EXTENDING IN .150" FROM THE PACKAGE PERIMETER MAY BE USED TO APPLY CONTACT PRESSURE. THIS AREA SHOULD BE FREE OF OBSTRUCTIONS SUCH AS THE LID OR CHIP CAPACITORS.
- B FOR SOME SOCKETING APPLICATIONS A MINIMUM PIN LENGTH OF .055" MAY BE REQUIRED. FOR CAVITY DOWN CONFIGURATIONS THIS DISTANCE IS MEASURED FROM THE LEAD TIP TO THE LID SURFACE.
- C FOR CLEANING OF CIRCUIT BOARDS AFTER COMPONENT MOUNTING IT IS RECOMMENDED THAT A MINIMUM DISTANCE OF .010" FROM THE LEAD TIP TO LID SURFACE IS MAINTAINED.

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